

Business Briefing

Functional Products Business

June 7, 2024

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FURUKAWA ELECTRIC CO., LTD.

Contents of today's briefing



- 1. 2025 Mid-term Plan Road to Vision 2030
 - (1) Basic policy and product lineup designed to solve social issues
 - (2) Market overview (medium-term)
 - (3) Policy & strategy
 - (4) Net sales & operating income (FY23 result, FY24 forecast, FY25 target)
- 2. FY24
 - (1) Policy & strategy
 - (2) Measures to grow the business and improve earnings, and net sales forecast

AT & Functional Plastics Division

Thermal Management Solution & Products Division

Memory Disk Division

Copper Foil Division

Main points of today's briefing



■ In FY23, the full-scale market recovery did not materialize, but there have recently been signs of a recovery.

The market is expected to grow in the medium-term.

■ In FY24, continue to grow by acquiring new domains and new customers through "high performance" and "well-differentiated" products.

■ Establish a system that can immediately respond when the market recovers during FY24.



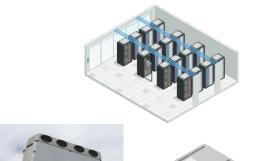
Functional products market and basic business policy

Basic policy - Overview



Create in partnership with the customer, and provide solutions

Support the growing telecommunications and social infrastructure markets by leveraging our proposal and development capabilities for new products that match customer needs





Infrastructure

Data centers

Base stations

Increased telecommunications speed and volume

> Generative Al, cloud, IoT, etc.

Terminals

Smartphones / tablets

Wearable devices

Al unit



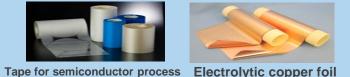
Functional product lineup that supports the growing telecommunications and social infrastructure markets

















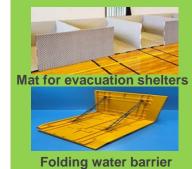


Renewable energy









Functional product lineup that supports the growing telecommunications and social infrastructure markets



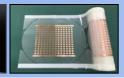
Social issues

■ INDUSTRY, INNOVATION AND INFRASTRUCTURE

Broad, characteristic lineup of high performance, well-differentiated products that respond to various social issues

Realize tougher infrastructure/ increased data traffic













Tape for 5G next-generation devices

Smart cities/ high performance troughs

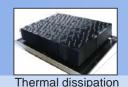
Thermal dissipation products for CPUs

Aluminum HDD blanks

Clean energy

Electrolytic copper foil for printed wiring boards

Realize a carbon free society/ renewable energy



products for solar power



Troughs for slopes



power station



at the copper foil plant





Use of renewable energy at the Imaichi Plant

Use of renewable energy at the plant in the Philippines

Realize cities that remain functional during disasters/ disaster prevention & mitigation







Folding water barrier



Exterior wall penetration



Moisture activated waterproofing

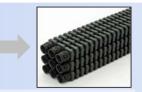












Foam recycling: EFLEX filler

Realize a recycling based society/ environmental recycling



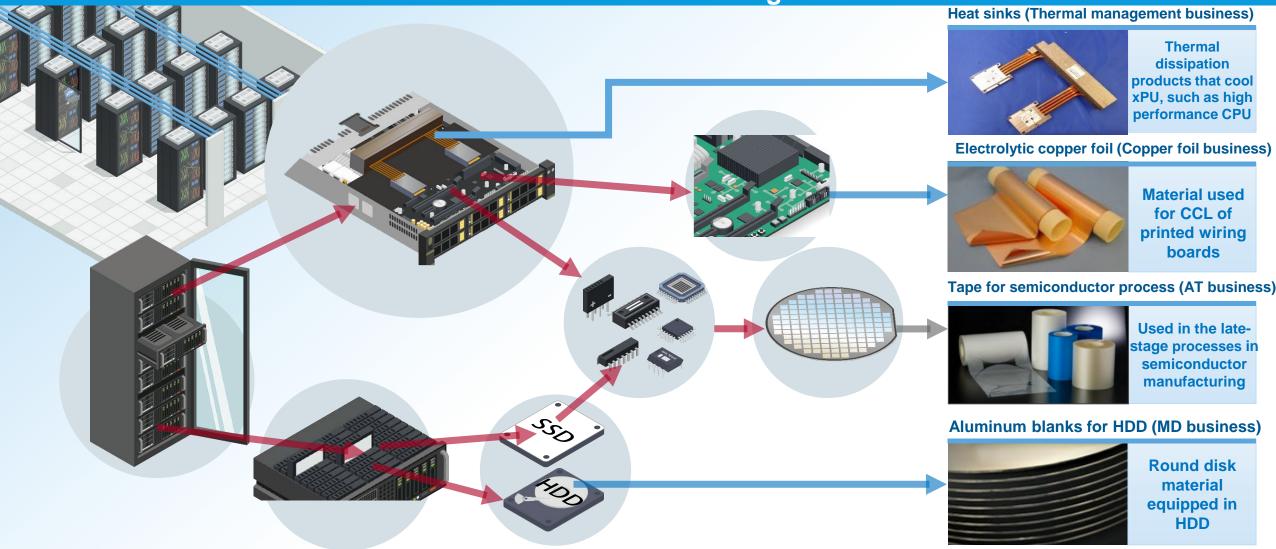


EFCELL packaging material **EFCELL** office supplies

Functional Products – Example of use at data centers



The products of the Functional Products business are used in many parts of high performance servers in data centers within the global market

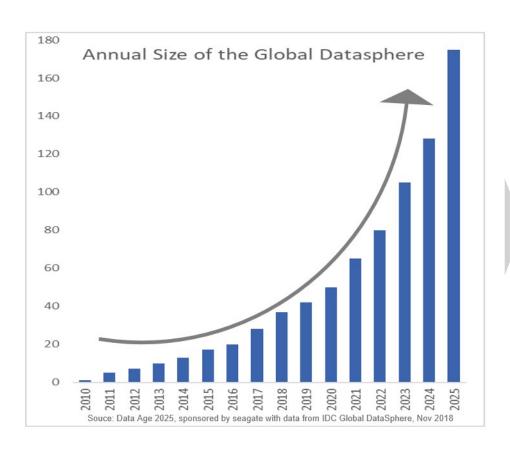


Market overview

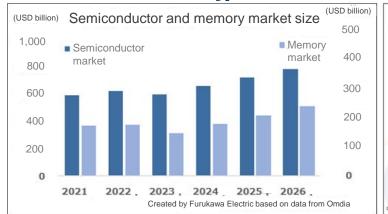


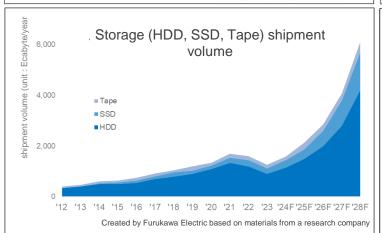
Focus on the trend markets, and provide "well-differentiated", "high performance" products to the related markets

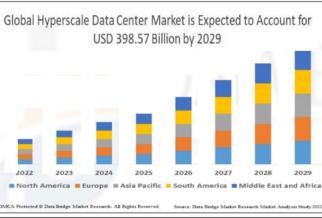
Although the market is currently undergoing a correction, the volume of data generated worldwide and data traffic will increase in the future

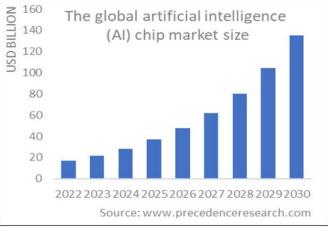


Most functional product businesses and product markets will grow in the medium-to long-term following the increased data volumes









Mid-term Plan

Road to Vision 2030 - Transform and Challenge -



Provide electronics products with an awareness of "high performance" and "well-differentiated" to growth markets

- 1. Continue to develop products aimed at swiftly responding to the changing customer requirements, provide electronics products with an awareness of "high performance" and "well-differentiated" to growth markets and support the telecommunications and social infrastructure markets
- 2. Contribute to realizing a sustainable society and secure the next generation profit base, by "differentiation" aimed at solving social issues as leveraging the new products directed at Society 5.0 for SDGs and creating a framework for becoming carbon neutral.

AT & Functional Plastics business

- Solve the technological issues arising from the increasingly sophisticated and complex semiconductor manufacturing processes, contribute to the evolution of semiconductors and support telecommunications and social infrastructure.
- Contribute to the renewable energy market and increasing national resilience through next-generation infrastructure (underground conduit system, etc.) and disaster prevention & mitigation products.
- Support 5G/6G infrastructure through high performance foam products.

Thermal Management Solution & Products business

- Continue to provide well-differentiated cooling solutions for maximizing the potential of semiconductors that continue to generate more heat.
- For the heat generated from semiconductors, provide next-generation cooling solutions, including water cooling and liquid immersion, and help customers save energy and decarbonize. Work to introduce clean energy at the main manufacturing sites.

Memory Disk business

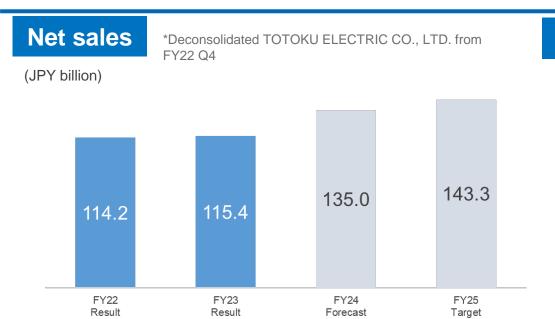
- Based on the technology accumulated over the past 50 years, continue to provide high performance materials to customers.
- Support safe, high quality storage infrastructure worldwide through the customer.

Copper Foil business

- Along with supplying highly reliable copper foil with characteristic features to CCL manufacturers and battery manufacturers, also supply to new customers in new domains.
- With the aim of developing new applications for electrolytic copper foil, create in partnership with customers in new domains in addition to existing customers.

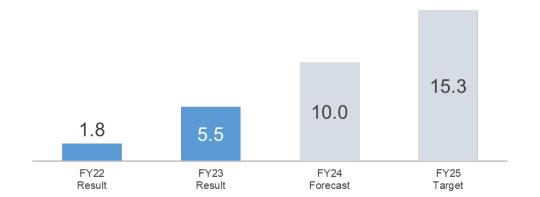
Net sales and operating income during the 2025 Mid-term Plan



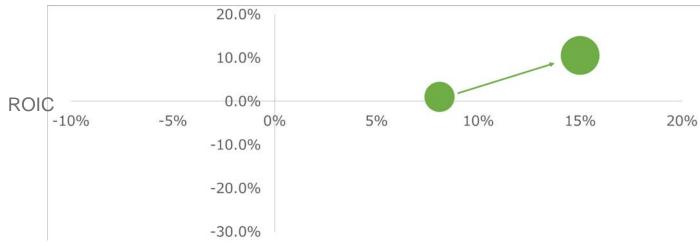


Operating income

(JPY billion)



ROIC (FY23 result → FY25 target)



Net sales CAGR

Vertical axis: Net sales CAGR (FY22-23→FY22-25)

Horizontal axis: ROIC (FY23→FY25) Bubble: NOPAT (FY23→FY25)

- * Net sales in FY25 used to calculate net sales CAGR have been adjusted based on the average exchange rate in the FY24 forecast
- * CAGR: Compound annual growth rate, ROIC: Return on invested capital (after taxes)
- NOPAT: Calculated as net income + interest expenses after tax in accordance with IFRS
- * Deconsolidated TOTOKU ELECTRIC CO., LTD. from FY22 Q4

FY24 Policy



Functional Products segment

- In FY24, continue to achieve growth by acquiring new customers in new domains through "high performance", "well-differentiated" products
- Establish a system that can immediately respond when market demand recovers this year

AT & Functional Plastics business

- Along with preparing a system for stable supply directed at the market recovery, aim to increase sales by promoting the development of technology for cutting edge processes, expanding conformance to the specifications for new projects and horizontal deployment.
- Roll out new developments in new domains that utilize next-generation infrastructure and foam technology, and promote new proposals for the disaster prevention & mitigation and renewable energy markets.
- Work to develop and increase sales of environmentally-friendly products.

Thermal Management Solution & Products business

- Through the provision of well-differentiated solutions and services, continue to contribute to solving social issues as a core partner, and increase topline sales.
- Quickly grasp the risks and opportunities based on global, market and customer trends, and increase profits by swiftly and proactively formulating and executing specific measures.

Memory Disk business

- Following the need for thinner blanks, aim to continue launching well-differentiated new materials onto the market.
- Increasing sales volumes of the high value-added thin blanks is KSF in the short and medium term, so continue to increase orders.

Copper Foil business

- As a true partner to customers, "quickly" develop new products that respond to changing customer requirements, and continue to provide new products with an awareness of "high performance" and "well-differentiated" to future growth markets.
- Based on a strong awareness of carbon neutrality, introduce renewable energy and actively work to save energy.



AT business and Functional Plastics business

[AT] Future outlook (1)



Contribute to the further evolution of semiconductors by solving the technology issues for cutting-edge processes

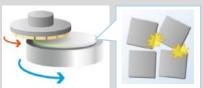
Technology trend

Issue faced by the customer

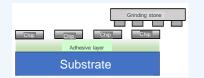
Solution provided by Furukawa Electric

Thinner wafers

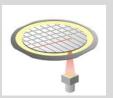
- Wafers are becoming thinner in order to increase memory performance through chip stacking
- In response to thinner wafers, a laser is used when cutting the wafer



As semiconductor chips become thinner, chipping occurs more easily during grinding

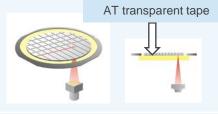


Optimize the conditions to prevent cracking by controlling the base film and adhesive properties





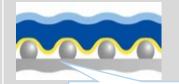
Standard tape has low transparency, making it impossible for the laser to cut the wafer



Tape with excellent transparency makes it possible to cut the wafer with a laser

Ultra-high bumps

•Use of FOWLP packages that enable increased chip density and high speed transmission is becoming more widespread. BG tape is attached to the surface of ultra-high bumps (solder bumps) and back grinding is conducted



If the tape does not follow the contour of the bumps closely, thickness precision is reduced and water may enter during grinding

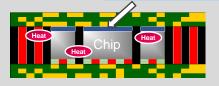
Achieve excellent contour fit for ultra-high bumps

Heat generation

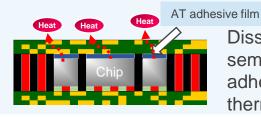
 Increased chip density results in larger amounts of heat generated



Water enters during grinding



Heat generated from increased chip density builds up in the package and reduces performance



Dissipate heat from the semiconductor chip using adhesive film with good thermal conductivity

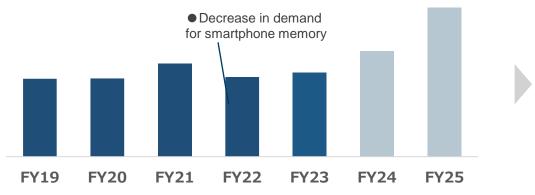
[AT] Future outlook (2)



Establish a system for stable supply directed at the semiconductor market recovery and demand growth

☐ Medium-to long-term demand growth in the semiconductor market

Sales of Furukawa Electric tape for semiconductor process



*Unified based on the new accounting standards

- From the second half of FY22, the global semiconductor market has been weak centered on memory for smartphones
- Market is expected to gradually recover from the second half of FY24 and continue to grow longterm thereafter

★ Establish a system for stable supply by increasing production capacity

Build the No 2 AT plant at the Mie Works

CAPEX: About JPY 7.0 billion (FY22-FY25)

September 2022: Commence

construction

May 2024: Open the plant and start trial of mass production

April 2025: Plan to start mass production

- Reuse waste heat energy
- Install solar power
 And implement other measures to reduce
 the environmental impact of the
 manufacturing process





[Functional Plastics] Future outlook



Contribute to building nextgeneration infrastructure

Total route design through systemized conduits

Square EFLEX







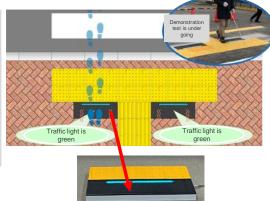
Develop new products directed at the next-

generation society

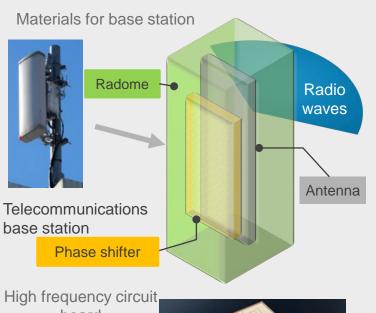
New conduits

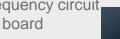


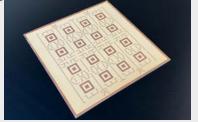
System to support high performance cross walks



Develop new markets and high performance products that use foam technology







Contribute to society through the development and sales of disaster prevention & mitigation products

Concluded a "Cooperation Agreement for Safe and Secure Town Development" with Hiratsuka City in Kanagawa Prefecture

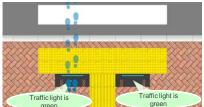


Folding water barrier



Mat for evacuation shelters



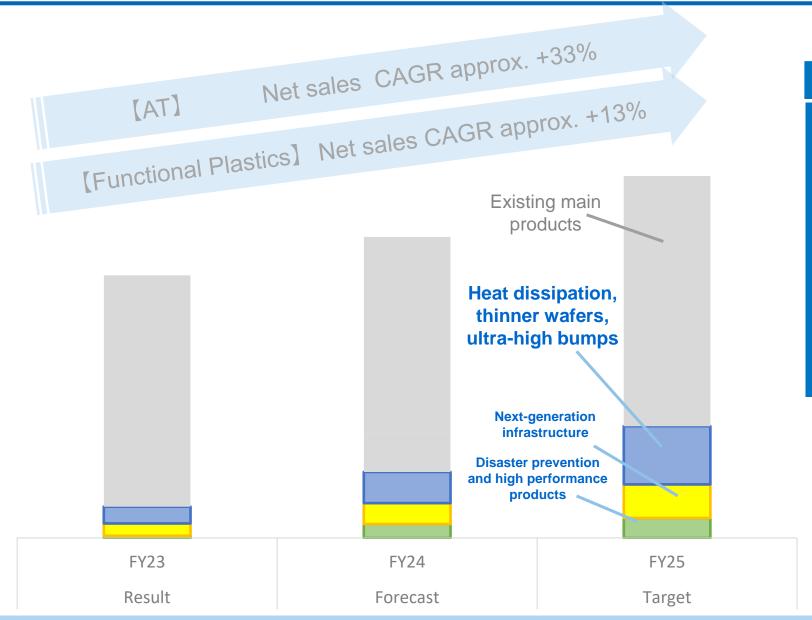


System to support high performance cross walks

Use recycled materials and raw materials not derived from fossil fuels

[AT & Functional Plastics] Net sales forecast





Point

Increased net sales by focusing on cutting edge semiconductor processes in AT, in businesses that provide solutions for a safety, peaceful and low environmental impact society in functional plastics

^{* &}quot;%" indicates the percentage of total sales

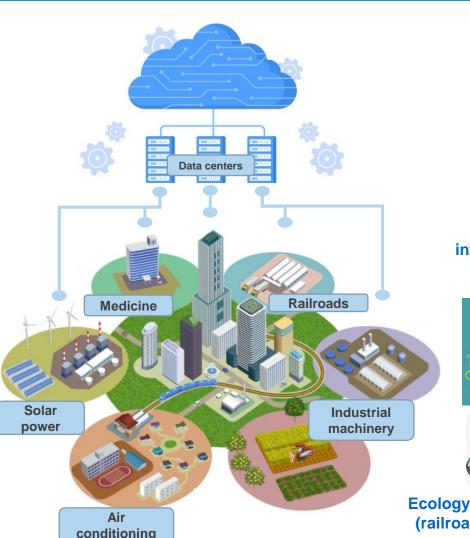


Thermal Management Solution & Products business

[Thermal Management Solution & Products] Future outlook



Develop and provide high performance, well-differentiated products for the issue of heat generation centered on the main production site (FTL in the Philippines)







Information infrastructure market (data centers)





Ecology infrastructure market (railroads, solar power, etc.)

More heat generated by CPUs and GPUs

- Provide air cooling method through high performance heat pipes & sinks and 3D vapor chambers
- Heat sinks for generative AI grew in FY23
- Participate in the area of water cooling and liquid immersion



Provide **one-stop solutions** that are lighter weight and include the use of **heat pipes and large vapor chambers**

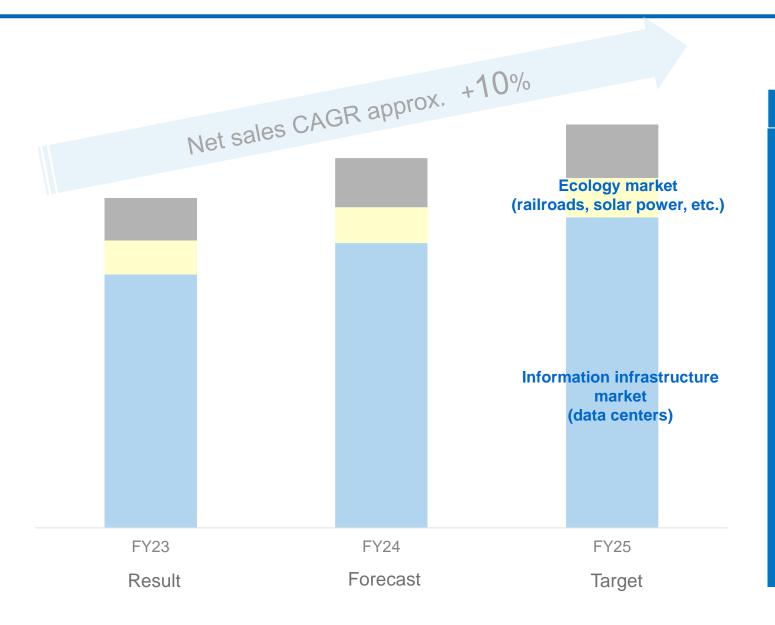




100% completion of clean energy installation at the main manufacturing site (FTL) for products for the data center market

[Thermal Management Solution & Products] Net sales forecast





Point

In FY23, in the data center market, heat sinks for generative Al grew significantly.

From FY24, provide well-differentiated products and services in the growing information infrastructure market, including participating in the area of water cooling and liquid immersion heat sinks, and work to increase profits.



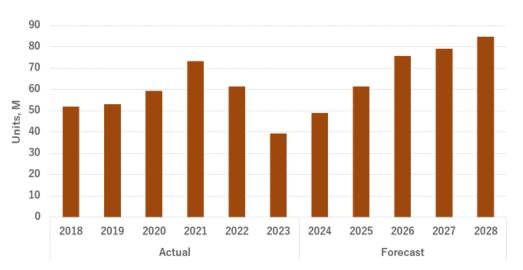
Memory Disk business

[Memory Disk] Future outlook



As blanks continue to become thinner, grow by responding to customer needs through well-differentiated materials

Changes in HDD shipments for nearline storage

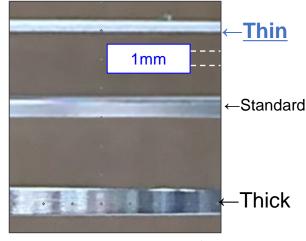


Created by Furukawa Electric based on materials from a research company

[Internal view of a new HDD] [Comparison of blank thickness]



Number of disks continues to increase, and there are now HDD with 10 disks

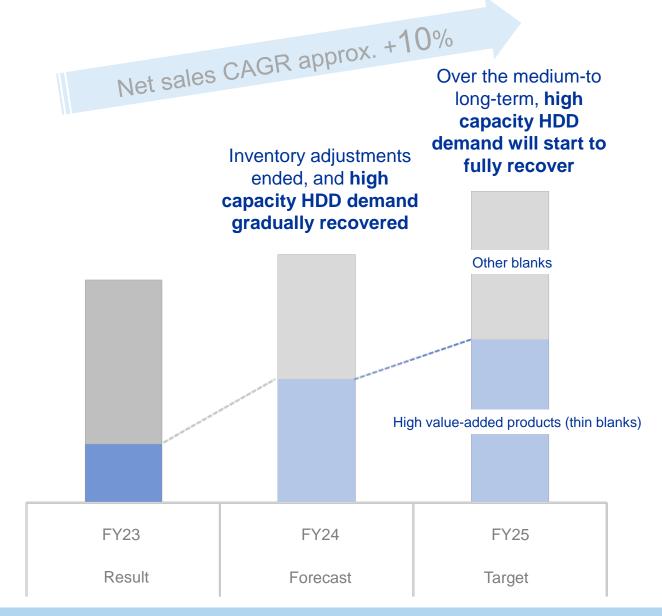


Thin blanks have a thickness of less than 1mm (Images are all Furukawa Electric blanks)

- ✓ As data volume increases, HDD will continue to be equipped with more disks per unit
- ✓ In order to increase the number of disks equipped, each disk will need to be thinner
- ✓ Respond to the customer need for <u>thinner</u>, and fulfill market expectations by launching well differentiated new materials

[Memory Disk] Net sales forecast





Point

- Although the market for high capacity HDD mainly for data centers has temporarily contracted, demand will remain strong over the medium- to long-term.
- •The capacity of each HDD unit continues to increase each year. As a result, there are growing requests for thinner, high quality blanks.
- •Continue to respond to customer needs by launching welldifferentiated new materials onto the market.



Copper Foil business

[Copper Foil] Future outlook



Continue to improve the product portfolio, such as focusing on copper foil for the growing high frequency circuit board market Develop & launch well-differentiated products using original surface processing technology

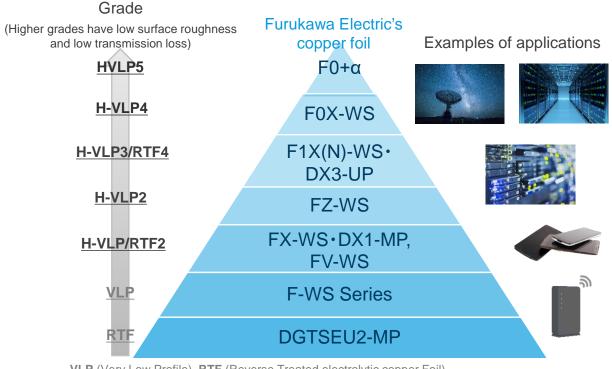
Create in partnership with the customer based on a high level of trust (quality, development capability) Continue to "improve the product mix" to high margin products with expected growth potential

Increased demand for AI servers following the launch of generative AI

2.500 2.000 1.500 Number 1,000 of units 500 2022 2023 2024F 2025F

(Graph: Forecast growth of Al servers (thousand units/year) Created by Furukawa Electric based on materials from a research company)

Furukawa Electric's high end copper foil is used in Al servers

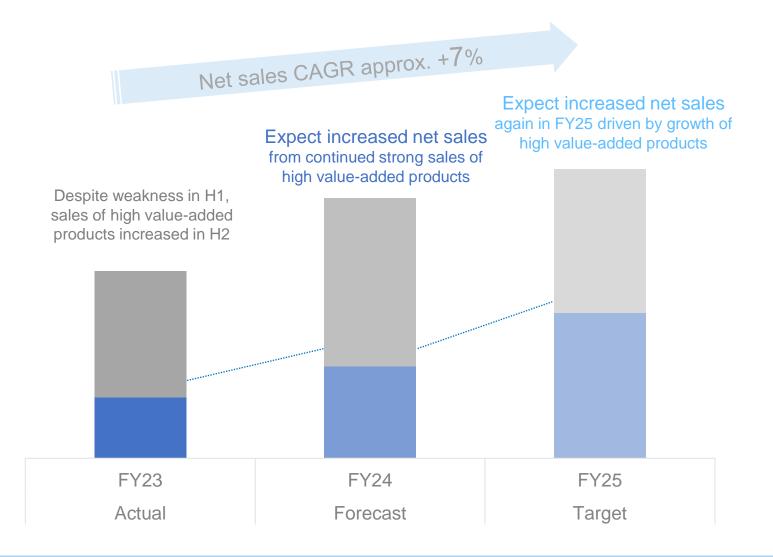


VLP (Very Low Profile), **RTF** (Reverse Treated electrolytic copper Foil)

[Copper Foil] Net sales forecast

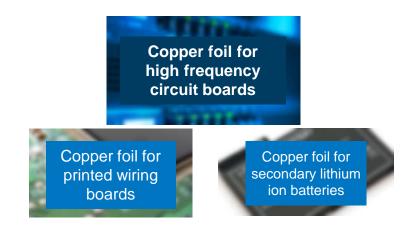


Led by copper foil for high frequency circuit boards, high value-added products will account for about 50% of net sales in FY2025



Point

Along with providing well-differentiated products with high reliability to customers, continue to develop new applications and provide to new customers.





Thank you very much for your attention



Appendix – Business overview





【2025 Mid-term Plan (Road to Vision 2030 -Transform and Challenge-) Basic policy】
Create in partnership with the customer, and provide solutions.
Support the growing telecommunications and social infrastructure markets by leveraging our strengths in proposing and developing products that match customer needs.

【Business environment, strengths and issues】

[Business environment, strengths and issues]				
Business environment – Main revenue opportunities	Strengths as a division			
 Further growth of telecommunications and social infrastructure demand resulting from increased data traffic and more widespread use of 5G Solving social issues such as SDGs and carbon neutral 	 Well-differentiated, strong technology development capability and patents Rapid, thorough customer service that combines engineering and sales 			
Business environment – Main menace and risks	Issues as a division			
 Supply instability within the supply chain caused by geopolitical risk Soaring raw material and transportation costs 	 Maintain and improve the design and development capabilities for continuing to generate well-differentiated technology Further promote the initiatives directed at further advancement of BCP through site optimization and reducing the environmental impact, including carbon neutral 			

[Main business strategy for achieving the 2025 Mid-term Plan]

- Continue to develop products aimed at swiftly responding to the changing customer requirements, provide electronics products with an awareness of "high performance" and "welldifferentiated" to growth markets and support the telecommunications and social infrastructure markets.
- Contribute to realizing a sustainable society and secure the next generation profit base, by "differentiation" aimed at solving social issues as leveraging the new products directed at Society 5.0 for SDGs and creating a framework for becoming carbon neutral.











Appendix – Product overview



Business		Functional Plastics anced Technology Tape	Thermal Management Solution & Products	Memory Disk	Copper Foil
Product images					
Renewable energy		•	•		
Telecommunications infrastructure	•	•	•	•	•
Mobility		•	•		•
Main products	Tape for semiconductor process	 Protective pipes for cables Troughs made from recycled materials Insulation materials 	High performance heat sinks and heat pipes, 3D vapor chambers and other thermal dissipation products	Aluminum blanks for HDD	Electrolytic copper foil for printed wiring boards Electrolytic copper foil for batteries
Main applications	 Surface protection, immobilization, etc. during semiconductor wafer processing 	 Protective pipes for underground cable Troughs for holding cables Insulation for air conditioning ducts 	 Thermal dissipation for CPUs and GPUs used in data center servers Thermal dissipation for power semiconductors used for railroads and renewable energy 	HDD for data centers, desktop computers, surveillance cameras, etc.	 Wiring boards for electronic devices, such as smartphones and PCs, and for high-end servers, such as AI servers and telecommunications servers Cathode material in lithium ion batteries for electric vehicles, smartphones, power tools, etc.
Main customers	 Semiconductor manufacturers Foundry manufacturers 	 General construction companies and subcontractors Railroad companies Highway public corporations and road subcontractors Air conditioning duct manufacturers 	 Data center and telecommunications base station operators Smartphone & PC manufacturers Railroad companies and power conditioner manufacturers PC & medical device manufacturers 	HDD substrate manufacturers	Wiring board material manufacturers Lithium ion battery manufacturers